

SID

Factory: Rot am See

Article:

ML6

Provided:

Customer:

Date:

03.04.2026

WÜRTH
ELEKTRONIK
MORE THAN
YOU EXPECT

Processtechnology: B: undefined

Material Text	Mat. Nr.	µm	Stackup	Process overview
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A-RS Kupferfolie-018my 330x490mm	50200238	18	VS	1	
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	168		2	
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	0		3	
		70	L2		
C-STD-FR4-ML-0.305mm-070+070-TG150-H...	50203120	305		4	A01
		70	L3		
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	183		5	
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	0		6	B00
		70	L4		
C-STD-FR4-ML-0.305mm-070+070-TG150-H...	50203120	305		7	A02
		70	L5		
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	168		8	
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	0		9	
A-RS Kupferfolie-018my 330x490mm	50200238	18	RS	10	

Thickness after Pressing

B00:

1440 µm

Tol+:

155 µm

Tol-:

155 µm

Dmax:

1595 µm

Dmin:

1285 µm

Thickness over all

0 µm

Tol+:

0 µm

Tol-:

0 µm

Dmax:

0 µm

Dmin:

0 µm

Demand for customer

Thickness (D):

1550 µm

Tol+:

155 µm

Tol-:

155 µm

Dmax:

1705 µm

Dmin:

1395 µm

Measuring point: (05) over SM and galv. Cu; both sides

nominal:

1445 µm

Version 1.2.20.35

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